



# Product Change Notification

## 105987 - 00

Information in this document is provided in connection with Intel products. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Intel's Terms and Conditions of Sale for such products, Intel assumes no liability whatsoever, and Intel disclaims any express or implied warranty, relating to sale and/or use of Intel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Intel products are not intended for use in medical, life saving, or life sustaining applications. Intel may make changes to specifications and product descriptions at any time, without notice.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific Contact:** [apacgccb@intel.com](mailto:apacgccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jccb.ijkk@intel.com](mailto:jccb.ijkk@intel.com)

Copyright © Intel Corporation 2006. Other names and brands may be claimed as the property of others.

AlertVIEW, AnyPoint, AppChoice, EtherExpress, FlashFile, i386, i486, i960, Intel, Celeron, Intel486, Intel740, IntelDX2, IntelDX4, IntelSX2, Itanium, LANDesk, LanRover, Pentium, Xeon, Intel Xeon, NetMerge, NetStructure, OverDrive, Paragon, PDCharm, StrataFlash is a trademark or registered trademarks of Intel Corporation or its subsidiaries in the United States and other countries.

Learn how to use Intel Trade Marks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.



# Product Change Notification

**Change Notification #:** 105987 - 00  
**Change Title:** Optical Networking 10/100 Repeater, PCN 105987-00, Product Design, LXT98xx.B4 and LXT9880.A5 to LXT98xx.A6, Conversion, Transition to RoHS, Order Code Change, Product Marking Change  
**Date of Publication:** March 02, 2006

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date of Samples Availability:</b>	Feb 28, 2006
<b>Date of Qualification Data Availability:</b>	Feb 28, 2006
<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	May 31, 2006
<b>Date of First Availability of Post-Conversion Material:</b>	Feb 28, 2006

*The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.*

## Description of Change to the Customer:

Intel will be migrating customers for the LXT98xx.B4 and LXT9880.A5 to a new stepping, the LXT98xx.A6. For customers using the LXT98xx.B4 this also reflects a change in wafer fabrication site. Stepping A5 and A6 are from the same wafer fabrication site.

- There is no change in the form, fit or function.
- The Erratum in the Specification Update has been fixed. (See Attachment 1)
- The product device ID changes to reflect the product stepping.

In order to be inline with Intel's Pb-free (Lead-free) and RoHS initiative we will be adopting a standard process for the products listed in the Products Affected Table below. During the standardization process the lead finish will be changed from Tin/Lead (Sn Pb) wave soldering to Tin Plating. Tin Plating is a Pb-free process. As a result of our investigation, to our knowledge the amount of cadmium, hexavalent chromium, mercury, polybrominated biphenyls (PBB), and polybrominated diphenyl ethers (PBDE) is either not detected or below the threshold targets for RoHS (Restriction on Hazardous Substances). Please see reference documents.

## Customer Impact of Change and Recommended Action:

Orders for B4 or A5 material will be converted to A6 material upon depletion of B4 inventory.

It is recommended that customers using the LXT98xx.B4/A5 silicon qualify the LXT98xx.A6 silicon for their designs. Samples and production parts for the LXT98XX.A6 silicon are available and customers are requested to start the qualification process at their earliest convenience.

The marketing package designator will also change to reflect Pb-free packaging. In order to facilitate this change a new MM# has been created for the affected products. Please see table below.

## Products Affected / Intel Ordering Codes:

### Component Product Table

Pre-Conversion Product Code	Pre-Conversion Spec/ROM	Pre-Conversion MM#	Post-Conversion Product Code	Post-Conversion Spec/ROM	Post-Conversion MM#
HBLXT9860AHC.B4		837730	WBLXT9860AHC.A6		882115
HBLXT9860AHC.B4	S E001	837732	WBLXT9860AHC.A6	S E001	882116
HBLXT9863AHC.B4		837734	WBLXT9863AHC.A6		882119
HBLXT9863AHC.B4	S E001	837735	WBLXT9863AHC.A6	S E001	882259
HBLXT9880AHC.B4		837736	WBLXT9880AHC.A6		882123
HBLXT9880AHC.B4	S E001	837737	WBLXT9880AHC.A6	S E001	882124
HBLXT9883AHC.B4		837738	WBLXT9883AHC.A6		882257
HBLXT9883AHC.B4	S E001	837739	WBLXT9883AHC.A6	S E001	882247
HDLXT9880AGE.B4		837896	WDLXT9880AGE.A6		882104
HDLXT9880AGE.B4	S E001	837897	WDLXT9880AGE.A6	S E001	882113
WDLXT9880AGE.A5	Q E000	873104	WDLXT9880AGE.A6		882104
WDLXT9880AGE.A5	S L8RC	873068	WDLXT9880AGE.A6	S E001	882113

## Reference Documents / Attachments:

**Document:**  
Material Declaration  
Data Sheet

**Location #:**

[http://download.intel.com/design/packtech/material\\_content\\_IC\\_Package.pdf#pagemode=bookmark](http://download.intel.com/design/packtech/material_content_IC_Package.pdf#pagemode=bookmark)

**Document:**  
Intel Lead Free  
Solutions

**Location #:**

<http://www.intel.com/research/silicon/leadfree.htm>

**Location #:**

**Attachment:**  
LXT98xx Specification  
Update



## **PCN Revision History:**

**Date of Revision:**

March 2, 2006

**Revision Number:**

00

**Reason:**

Originally Published PCN